

IRLI520NPbF

- Lead-Free
- Logic-Level Gate Drive
- Advanced Process Technology
- Isolated Package
- High Voltage Isolation = 2.5KVRMS ⑤
- Sink to Lead Creepage Dist. = 4.8mm
- Fully Avalanche Rated

Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The TO-220 Fullpak eliminates the need for additional insulating hardware in commercial-industrial applications. The moulding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The Fullpak is mounted to a heatsink using a single clip or by a single screw fixing.

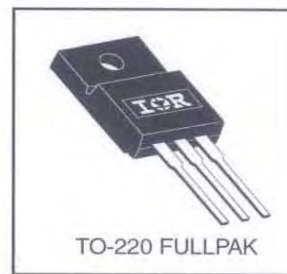
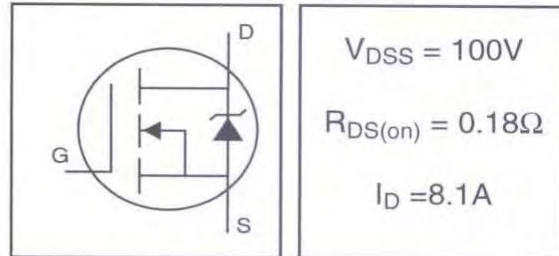
Absolute Maximum Ratings

| | Parameter | Max. | Units |
|---------------------------------|---|--------------------|-------|
| $I_D @ T_C = 25^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ 10\text{V}$ | 8.1 | A |
| $I_D @ T_C = 100^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ 10\text{V}$ | 5.7 | |
| I_{DM} | Pulsed Drain Current ①⑥ | 35 | |
| $P_D @ T_C = 25^\circ\text{C}$ | Power Dissipation | 30 | W |
| | Linear Derating Factor | 0.20 | W/°C |
| V_{GS} | Gate-to-Source Voltage | ± 16 | V |
| E_{AS} | Single Pulse Avalanche Energy ②⑥ | 85 | mJ |
| I_{AR} | Avalanche Current ①⑥ | 6.0 | A |
| E_{AR} | Repetitive Avalanche Energy ① | 3.0 | mJ |
| dv/dt | Peak Diode Recovery dv/dt ③⑥ | 5.0 | V/ns |
| T_J | Operating Junction and | -55 to + 175 | °C |
| T_{STG} | Storage Temperature Range | | |
| | Soldering Temperature, for 10 seconds | | |
| | Mounting torque, 6-32 or M3 screw | 10 lbf•in (1.1N•m) | |

Thermal Resistance

| | Parameter | Typ. | Max. | Units |
|-----------------|---------------------|------|------|-------|
| $R_{\theta JC}$ | Junction-to-Case | — | 5.0 | °C/W |
| $R_{\theta JA}$ | Junction-to-Ambient | — | 65 | |

HEXFET® Power MOSFET



Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|--|--------------------------------------|------|------|------|-------|---|
| V _{(BR)DSS} | Drain-to-Source Breakdown Voltage | 100 | — | — | V | V _{GS} = 0V, I _D = 250μA |
| ΔV _{(BR)DSS} /ΔT _J | Breakdown Voltage Temp. Coefficient | — | 0.11 | — | V/°C | Reference to 25°C, I _D = 1mA ^⑥ |
| R _{DS(on)} | Static Drain-to-Source On-Resistance | — | — | 0.18 | Ω | V _{GS} = 10V, I _D = 6.0A ^④ |
| | | — | — | 0.22 | | V _{GS} = 5.0V, I _D = 6.0A ^④ |
| | | — | — | 0.26 | | V _{GS} = 4.0V, I _D = 5.0A ^④ |
| V _{GS(th)} | Gate Threshold Voltage | 1.0 | — | 2.0 | V | V _{DS} = V _{GS} , I _D = 250μA |
| g _{fs} | Forward Transconductance | 3.1 | — | — | S | V _{DS} = 25V, I _D = 6.0A ^⑥ |
| I _{DSS} | Drain-to-Source Leakage Current | — | — | 25 | μA | V _{DS} = 100V, V _{GS} = 0V |
| | | — | — | 250 | | V _{DS} = 80V, V _{GS} = 0V, T _J = 150°C |
| I _{GSS} | Gate-to-Source Forward Leakage | — | — | 100 | nA | V _{GS} = 16V |
| | Gate-to-Source Reverse Leakage | — | — | -100 | | V _{GS} = -16V |
| Q _g | Total Gate Charge | — | — | 20 | nC | I _D = 6.0A |
| Q _{gs} | Gate-to-Source Charge | — | — | 4.6 | | V _{DS} = 80V |
| Q _{gd} | Gate-to-Drain ("Miller") Charge | — | — | 10 | | V _{GS} = 5.0V, See Fig. 6 and 13 ^{④⑥} |
| t _{d(on)} | Turn-On Delay Time | — | 40 | — | ns | V _{DD} = 50V |
| t _r | Rise Time | — | 35 | — | | I _D = 6.0A |
| t _{d(off)} | Turn-Off Delay Time | — | 23 | — | | R _G = 11Ω, V _{GS} = 5.0V |
| t _f | Fall Time | — | 22 | — | | R _D = 8.2Ω, See Fig. 10 ^{④⑥} |
| L _D | Internal Drain Inductance | — | 4.5 | — | nH | Between lead, 6mm (0.25in.) from package and center of die contact |
| L _S | Internal Source Inductance | — | 7.5 | — | | |
| C _{ISS} | Input Capacitance | — | 440 | — | pF | V _{GS} = 0V |
| C _{OSS} | Output Capacitance | — | 97 | — | | V _{DS} = 25V |
| C _{RSS} | Reverse Transfer Capacitance | — | 50 | — | | f = 1.0MHz, See Fig. 5 ^⑥ |
| C | Drain to Sink Capacitance | — | 12 | — | | f = 1.0MHz |

Source-Drain Ratings and Characteristics

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|-----------------|--|--|------|------|-------|---|
| I _S | Continuous Source Current (Body Diode) | — | — | 8.1 | A | MOSFET symbol showing the integral reverse p-n junction diode. |
| I _{SM} | Pulsed Source Current (Body Diode) ^{①⑥} | — | — | 35 | | |
| V _{SD} | Diode Forward Voltage | — | — | 1.3 | V | T _J = 25°C, I _S = 6.0A, V _{GS} = 0V ^④ |
| t _{rr} | Reverse Recovery Time | — | 110 | 160 | ns | T _J = 25°C, I _F = 6.0A |
| Q _{rr} | Reverse Recovery Charge | — | 410 | 620 | nC | di/dt = 100A/μs ^{④⑥} |
| t _{on} | Forward Turn-On Time | Intrinsic turn-on time is negligible (turn-on is dominated by L _S +L _D) | | | | |

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② Starting T_J = 25°C, L = 4.7mH
R_G = 25Ω, I_{AS} = 6.0A. (See Figure 12)
- ③ I_{SD} ≤ 6.0A, di/dt ≤ 340A/μs, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 175°C
- ④ Pulse width ≤ 300μs; duty cycle ≤ 2%.
- ⑤ t=60s, f=60Hz
- ⑥ Uses IRL520N data and test conditions

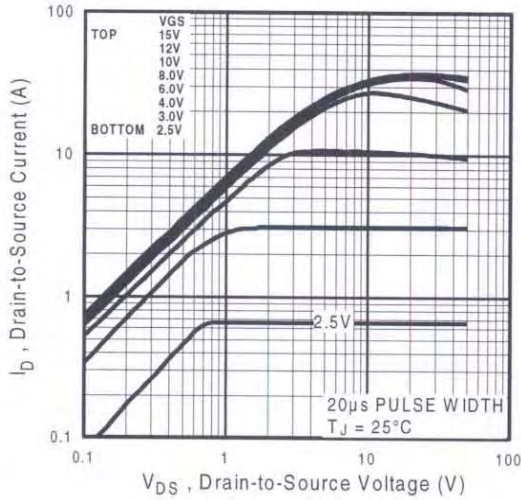


Fig 1. Typical Output Characteristics

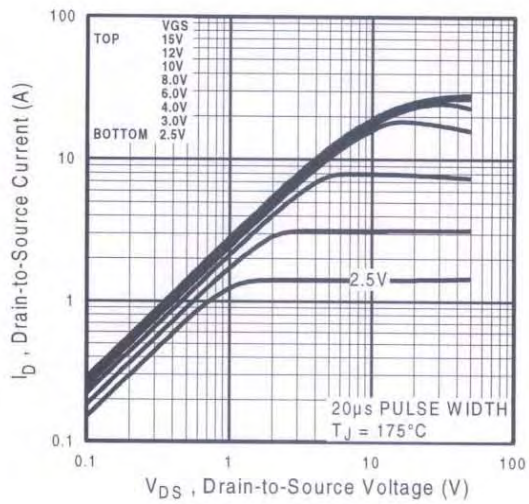


Fig 2. Typical Output Characteristics

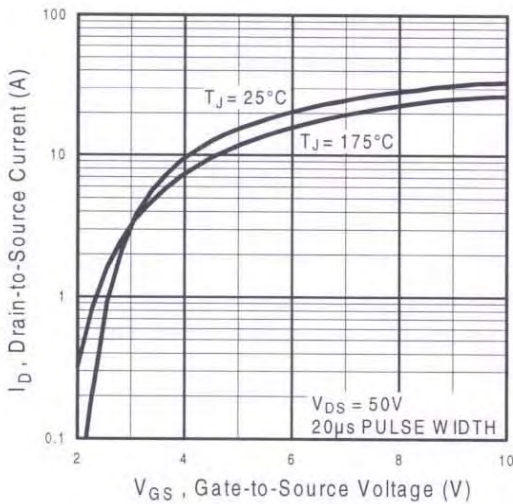


Fig 3. Typical Transfer Characteristics

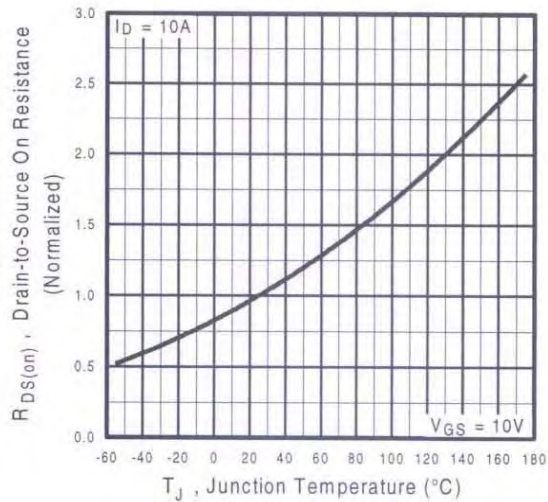


Fig 4. Normalized On-Resistance Vs. Temperature

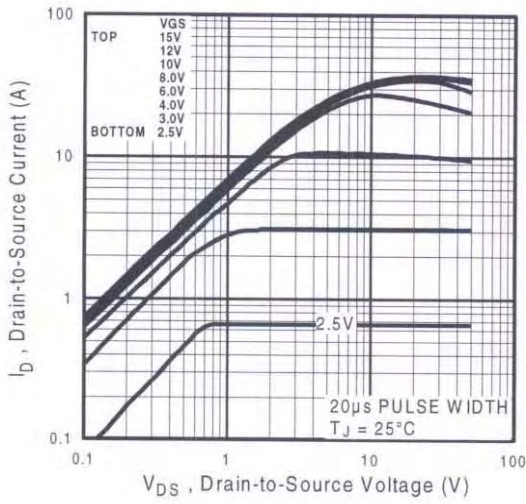


Fig 1. Typical Output Characteristics

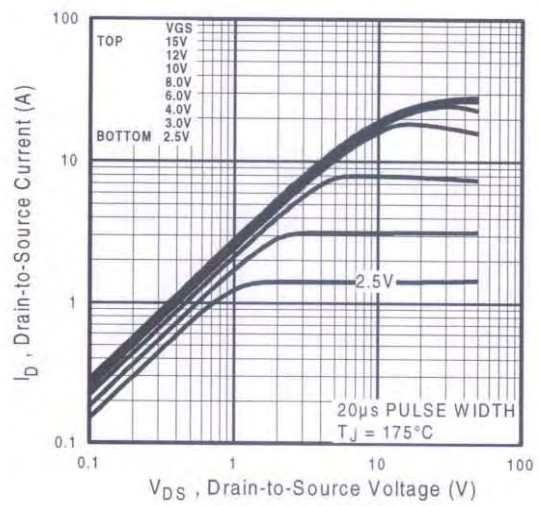


Fig 2. Typical Output Characteristics

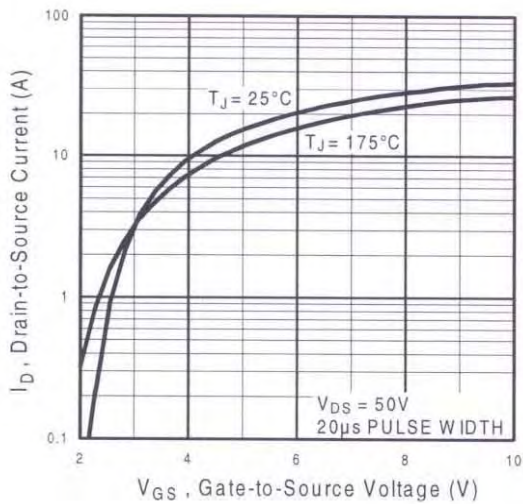


Fig 3. Typical Transfer Characteristics

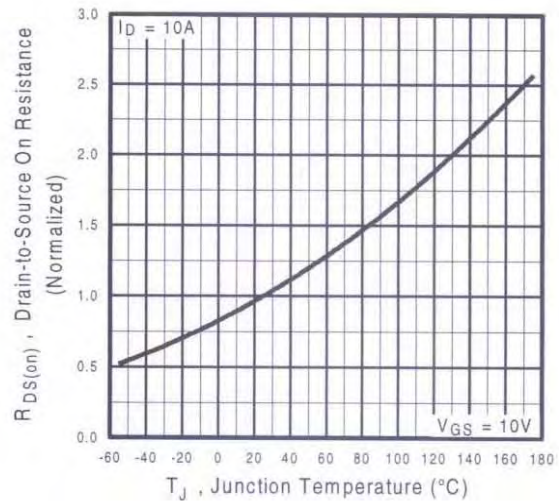


Fig 4. Normalized On-Resistance Vs. Temperature

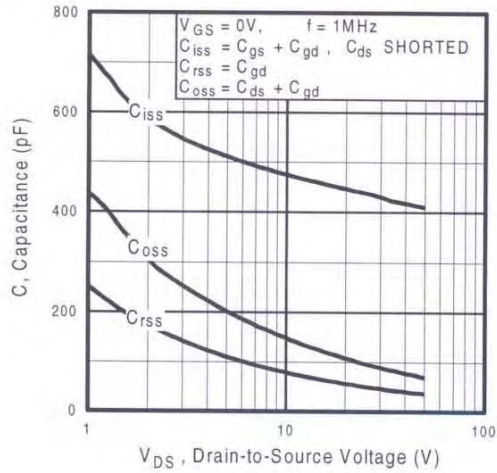


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

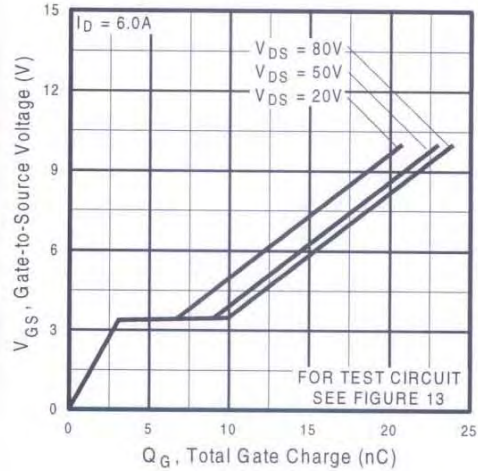


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

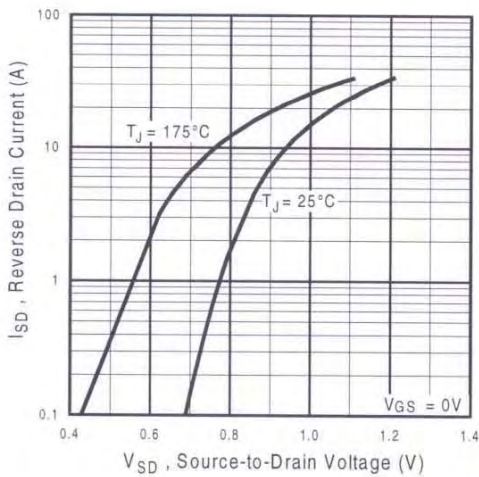


Fig 7. Typical Source-Drain Diode Forward Voltage

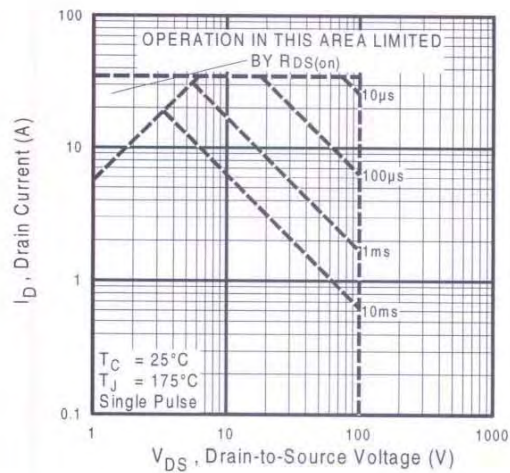


Fig 8. Maximum Safe Operating Area

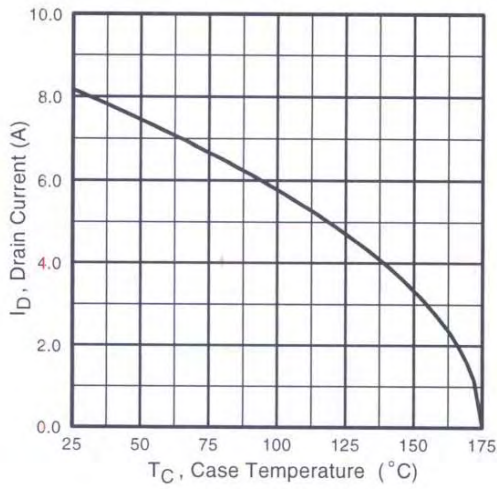


Fig 9. Maximum Drain Current Vs. Case Temperature

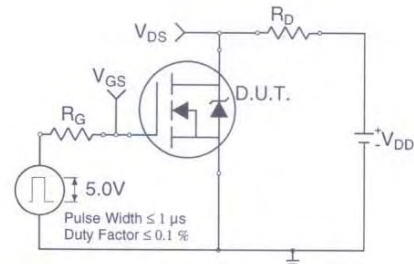


Fig 10a. Switching Time Test Circuit

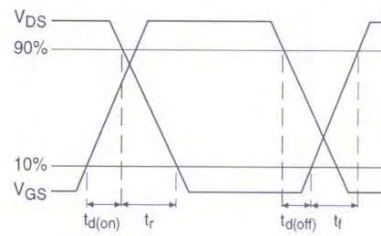


Fig 10b. Switching Time Waveforms

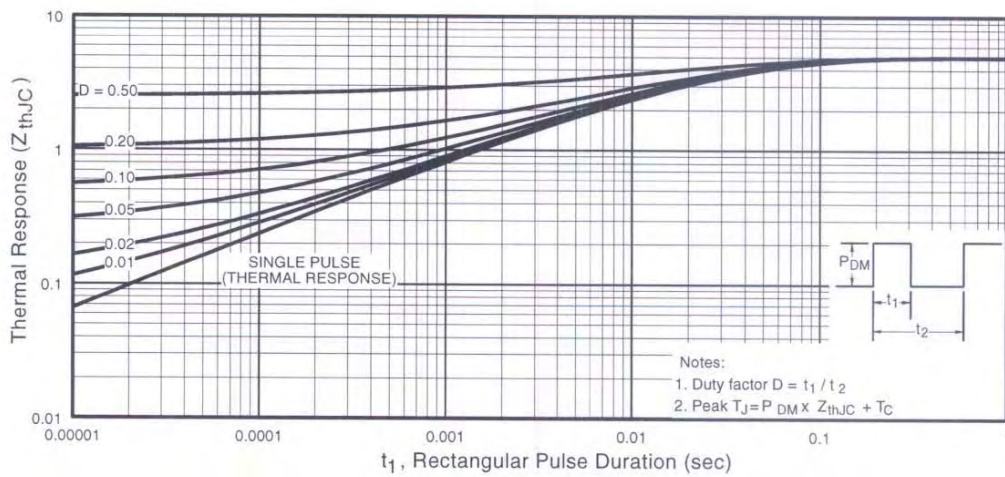


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

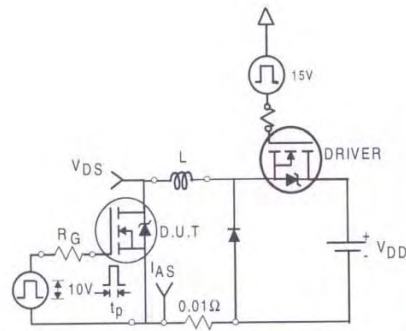


Fig 12a. Unclamped Inductive Test Circuit

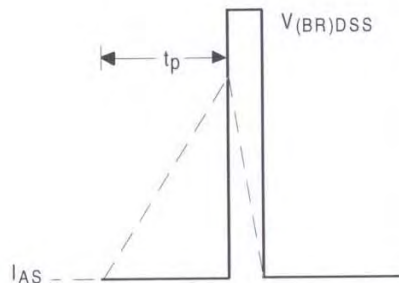


Fig 12b. Unclamped Inductive Waveforms

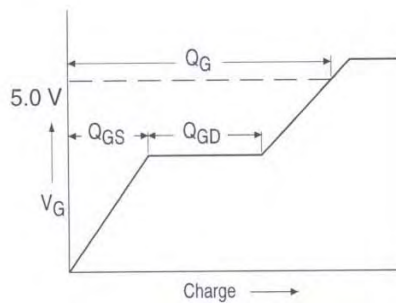


Fig 13a. Basic Gate Charge Waveform

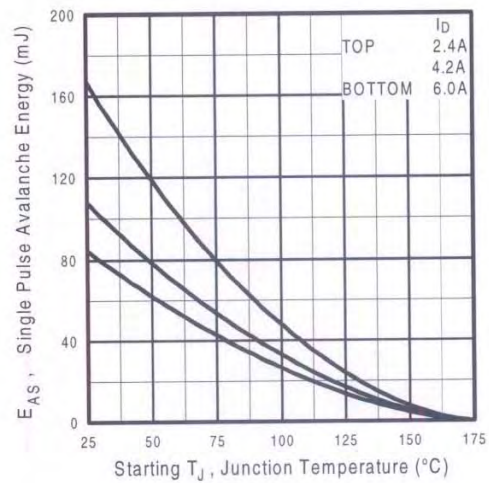


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

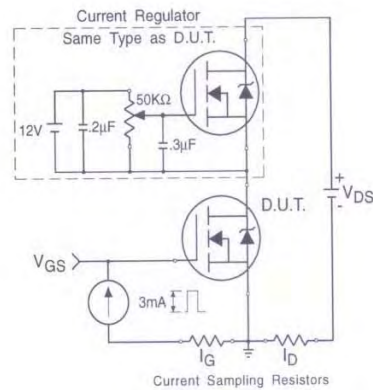
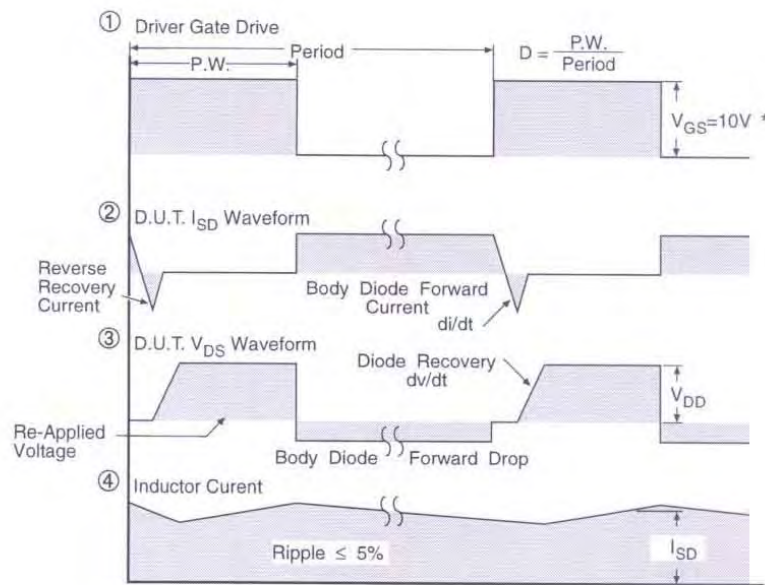
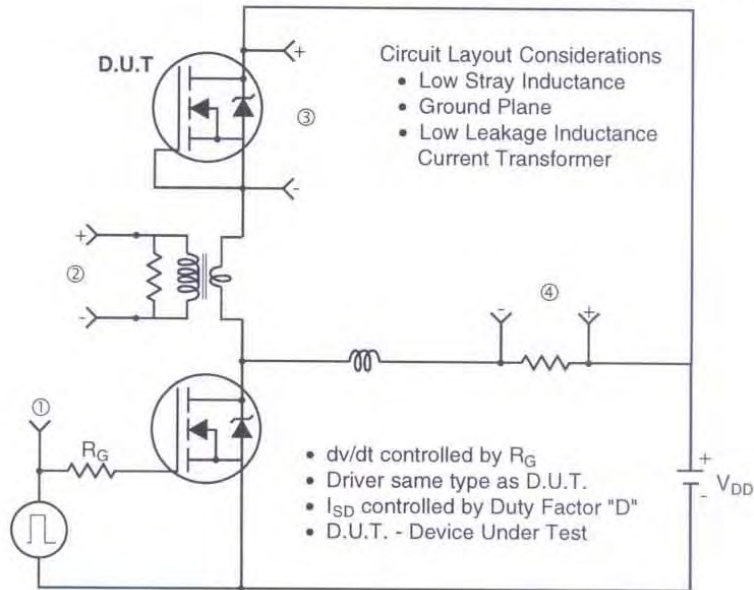


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit

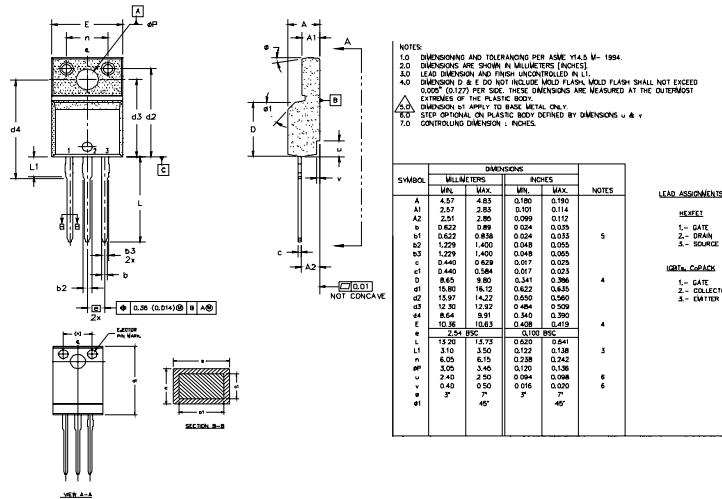


* $V_{GS} = 5V$ for Logic Level Devices

Fig 14. For N-Channel HEXFETS

TO-220 Full-Pak Package Outline

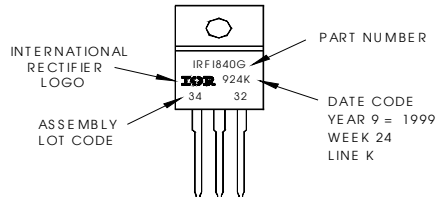
Dimensions are shown in millimeters (inches)



TO-220 Full-Pak Part Marking Information

EXAMPLE: THIS IS AN IRF1840G
 WITH ASSEMBLY
 LOT CODE 3432
 ASSEMBLED ON WW 24 1999
 IN THE ASSEMBLY LINE "K"

Note: "P" in assembly line position indicates "Lead-Free"



Data and specifications subject to change without notice.

Note: For the most current drawings please refer to the IR website at:
<http://www.irf.com/package/>

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